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TI Fine copper wires and their manufacture

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SO Jpn. Kokai Tokkyo Koho, 6 pp.

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DT Patent

LA Japanese

FAN.CNT 1

4.1%

PATENT NO. KIND DATE APPLICATION NO. DATE

PI JP 6323<u>5442</u> A2 19880930 JP 1987-69591 19870324 AB The wires (Cu purity .gtoreg.99.999

The wires (Cu purity .gtoreq.99.999.8) esp. for electronic devices are manufd. from Cu contg. Fe, Ag, and/or Sn 0.1-9 and Zr 0.1-2.5 ppm, with the total amt. of the alloying elements 0.2-9.5 ppm, by melting and casting in vacuum or nonoxidizing atm., drawing at final drawing ratio r = 70-99.98, and annealing to give elongation e = 2-20%. Thus, Cu contg. Zr 0.8 and Fe 4.2 ppm was melted, cast into a 25 .times. 140-mm billet, machined to 20 .times. 100-mm specimen, hot rolled to 10-mm diam., drawn at r = 92%, vacuum annealed at 350.degree. to 25-.mu.m-diam. wire, and finally annealed at 250-400.degree. in Ar. The resp. rupturing load and elongation for the obtained wire were 12.3 g and 14.3% vs. 12.1 g and

for the conventional fine Au wire. The obtained Cu wire also showed excellent bonding properties.